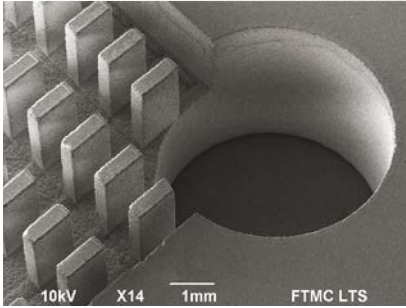


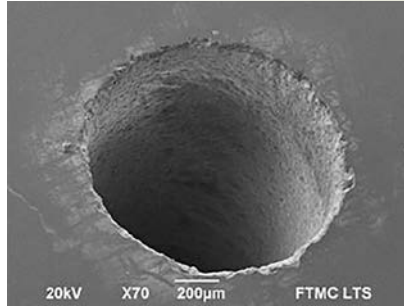
# Material processing samples

## GLASS MILLING



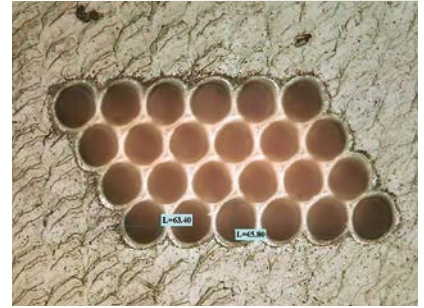
Surface chipping <100 μm, sidewall roughness <2 μm. Courtesy of FTMC.

## GLASS DRILLING



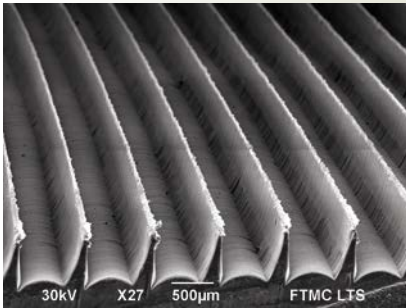
Surface chipping <100 μm, sidewall roughness <2 μm. Courtesy of FTMC.

## POLYAMIDE DRILLING



Drilling of 65 μm holes in 0.8 mm PI

## TEFLON ABLATION



Teflon (PTFE) ablation. Courtesy of FTMC.

## NICKEL ABLATION



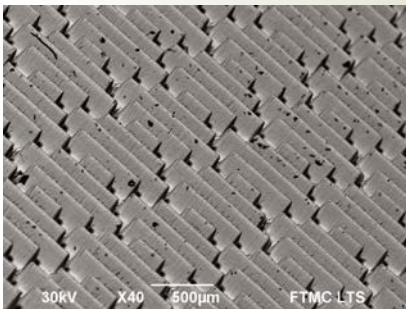
Ablation of 50 μm nickel layer from a ceramic substrate.

## COPPER ABLATION



Copper removal from PCB with down to <20 μm resolution.

## SURFACE STRUCTURING



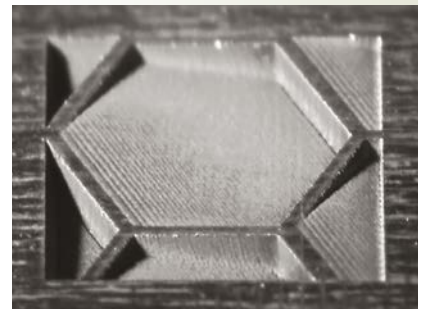
"Shark skin" surface structuring. Courtesy of FTMC.

## STAINLESS STEEL MARKING



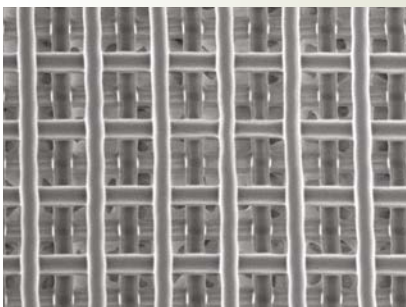
Highly resistant stainless steel black marking

## COPPER ABLATION



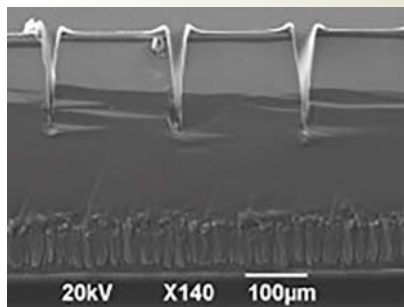
Surface roughness of 0.2 μm. Courtesy of Leibnitz IOM.

## PHOTOPOLYMERIZATION



Courtesy of Workshop of Photonics.

## SILICON SCRIBING



Courtesy of FTMC.

## COPPER DEEP 3D ENGRAVING



Courtesy of FTMC.